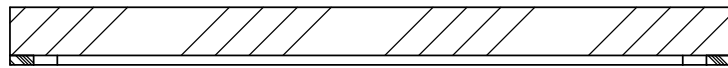
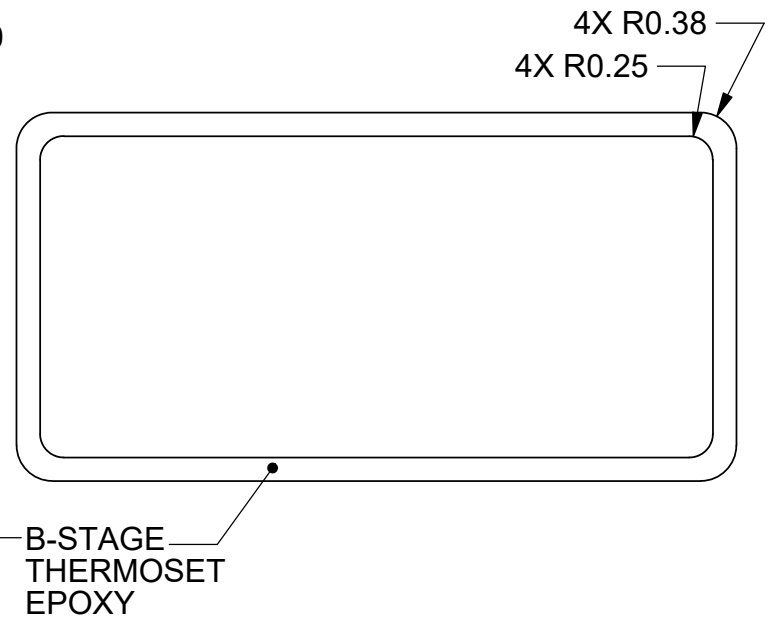
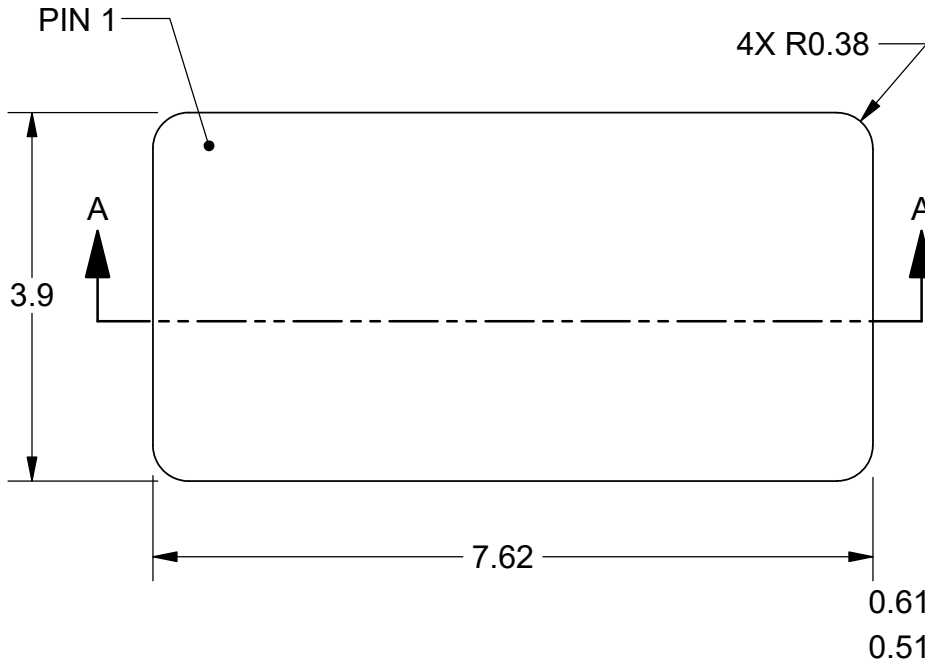


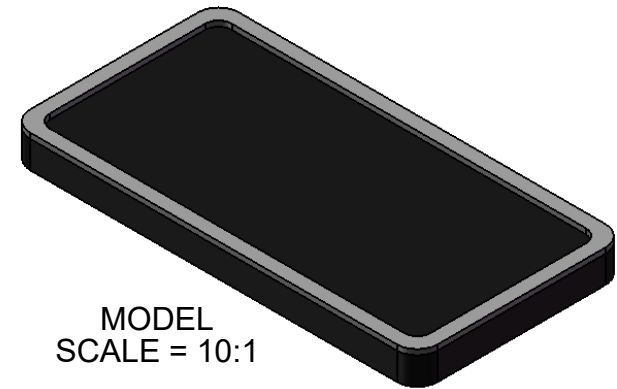
TOP VIEW

SIDE VIEW

BOTTOM VIEW




SECTION A-A



MODEL
SCALE = 10:1

NOTES: (UNLESS OTHERWISE SPECIFIED).

- 1) MATERIAL:
 - A) LID: SEMICONDUCTOR GRADE MOLD.
 - B) PREFORM: B-STAGE THERMOSET EPOXY.
- 2) RECOMENDED CURE: WITH CLAMP PRESSURE 0.035 KG/CM SQ.
 - STEP 1 - PREHEAT PACKAGE @ 75°C.
 - STEP 2 - CURE @ 125°C FOR 30 MINUTES.
 - STEP 3 - CURE @ 150°C FOR 60 MINUTES.
- 3) STORAGE LIFE: 6 MONTHS @ 25°C, 12 MONTHS @ 0°C.
- 4) DIMENSIONS IN MM.

TOLERANCE UNLESS NOTED		APPROVALS	DATE				
X.X	+/- 0.3						
X.XX	+/- 0.03	DRAWN J. Hines	5/18/2017	TITLE PLASTIC LID FOR SOICS WITH B-STAGE EPOXY			
X.XXX	+/- 0.003	ENG M. Hart	5/18/2017				
ANGLES +/- 0.5°		MFG		SCALE	SIZE	DRAWING NO.	REV
ALL DIMENSIONS IN		QA		12.5:1	A	276053	A
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		CUST		DO NOT SCALE DRAWING		SHEET 1 OF 1	
THIRD ANGLE PROJECTION		REVISED					